



DDR3 DIMM, DDR3 SO DIMM

TE Internal #: 4-1932000-8

DIMM Sockets, Double Data Rate (DDR) 3, Board-to-Board, 240 Position, Through Hole - Solder, Vertical Module Orientation, DDR3 DIMM

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR3 DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 3**

Connector System: **Board-to-Board**

Number of Positions: **240**

Termination Method to Printed Circuit Board: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR3 DIMM Sockets \(13\)](#)

Features

Product Type Features

| | |
|-----------------------------------|--------------------------|
| DRAM Type | Double Data Rate (DDR) 3 |
| Connector System | Board-to-Board |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|---------------------|----------|
| Number of Positions | 240 |
| Module Orientation | Vertical |

Body Features

| | |
|--------------|----------|
| Ejector Type | Standard |
|--------------|----------|

Contact Features

| | |
|------------------------------|-------|
| Contact Current Rating (Max) | .75 A |
|------------------------------|-------|

Termination Features

| | |
|---|-----------------------|
| Termination Method to Printed Circuit Board | Through Hole - Solder |
|---|-----------------------|

Mechanical Attachment

| | |
|--------------------------|-------------|
| PCB Mount Retention Type | Boardlock |
| Connector Mounting Type | Board Mount |

Housing Features



| | |
|--------------------|---------------|
| Centerline (Pitch) | 1 mm[.039 in] |
|--------------------|---------------|

Dimensions

| | |
|--------------------|-----------------|
| Row-to-Row Spacing | 1.9 mm[.075 in] |
|--------------------|-----------------|

Usage Conditions

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|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 155 °C[-67 – 311 °F] |
|-----------------------------|----------------------------|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Packaging Features

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|------------------|------------------|
| Packaging Method | Box & Tray, Tray |
|------------------|------------------|

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|------------------------------|-----------|
| EU RoHS Directive 2011/65/EU | Compliant |
|------------------------------|-----------|

| | |
|-----------------------------|-----------|
| EU ELV Directive 2000/53/EC | Compliant |
|-----------------------------|-----------|

| | |
|---|---|
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
|---|---|

| | |
|--|---|
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
|--|---|

| | |
|-----------------|--|
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
|-----------------|--|

| | |
|---------------------------|------------------------------|
| Solder Process Capability | Wave solder capable to 260°C |
|---------------------------|------------------------------|

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

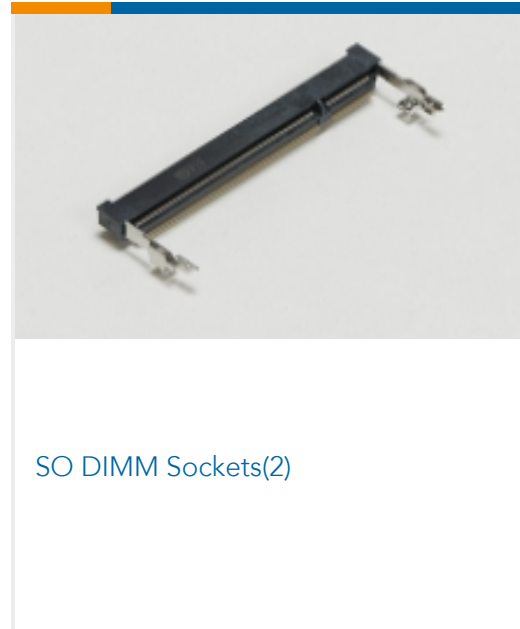
Compatible Parts



Also in the Series | **DDR3 DIMM**

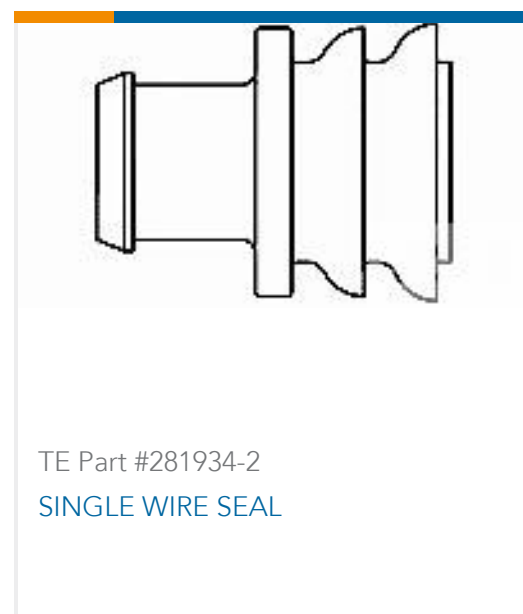


Also in the Series | **DDR3 SO DIMM**



Customers Also Bought





Documents

Product Drawings

[VERTICAL DDR3 DIMM, 240 POSITION](#)

English

CAD Files

Customer View Model

[ENG_CVM_CVM_4-1932000-8_F.2d_dxf.zip](#)

English

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_4-1932000-8_F.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_4-1932000-8_F.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[6-1773457-3_DDR3_DIMM_SOCKETS](#)

Product Specifications

[Product Specification](#)

English